

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) An ink jet printhead which comprises:
at least one printhead chip that comprises a wafer substrate; a plurality an array of
~~nozzle arrangements positioned~~ nozzles on the a wafer substrate, each nozzle arrangement
having ~~nozzle chamber walls and a roof wall that define a nozzle chamber and,~~ a nozzle
opening in fluid communication with said nozzle chamber; and ~~an~~ a thermal bend actuator
~~that is operatively arranged with respect to each the nozzle arrangement chamber to eject ink~~
~~from said nozzle chamber through the nozzle opening on demand; and~~
a nozzle guard ~~positioned over~~ comprising a cover member having a thickness of
less than approximately 300 microns which covers the printhead chip, the nozzle guard
comprising a support structure that extends from the printhead chip; and a planar cover
member positioned on the support structure array of nozzles, the planar cover member
defining a plurality of passages, each passage being spaced from and in register with a
respective nozzle opening such that ink ejected through the nozzle openings passes through
the respective passages, the planar cover member being less than approximately 300 microns
thick.
2. (Cancelled)
3. (Cancelled)
4. (New) An ink jet printhead as claimed in claim 1, wherein the nozzle guard further
comprises a plurality of struts which support the cover member in spaced relationship with
the nozzles.
5. (New) An ink jet printhead as claimed in claim 1, wherein the nozzle guard is part of
the wafer substrate.
6. (New) An ink jet printhead as claimed in claim 5, wherein the wafer substrate is a
silicon substrate.